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Atty. Dkt. No. 039153-0457 (G1162)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Unknown

Art Unit: Unknown

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below.	
<u>CHRIS ESCAVAILLE</u>	(Printed Name)
<u>Chris Escaville</u>	(Signature)
<u>9-23-02</u>	(Date of Deposit)

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

ATTENTION: DRAWING REVIEW BRANCH

Sir:

Transmitted herewith are the formal drawings (9 sheets, Figures 1-7) for the above-identified application. The Official Draftsperson is respectfully requested to approve these drawings for entry into the application.

Respectfully submitted,

Date Sept. 23, 2002

By Paul S. Hunter

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